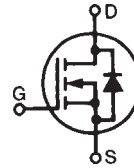


# PolarHV™ HiPerFET Power MOSFET

**IXFH 26N50P**  
**IXFV 26N50P**  
**IXFV 26N50PS**

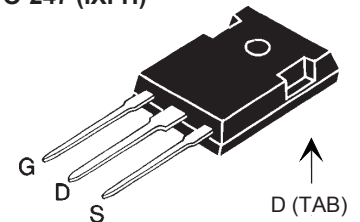
$V_{DSS} = 500 \text{ V}$   
 $I_{D25} = 26 \text{ A}$   
 $R_{DS(on)} \leq 230 \text{ m}\Omega$   
 $t_{rr} \leq 200 \text{ ns}$

N-Channel Enhancement Mode  
Avalanche Rated  
Fast Intrinsic Diode

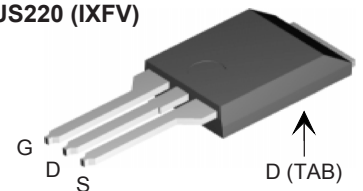


Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	500	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1 \text{ M}\Omega$	500	V
$V_{GSS}$	Continuous	$\pm 30$	V
$V_{GSM}$	Transient	$\pm 40$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$	26	A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	78	A
$I_{AR}$	$T_C = 25^\circ\text{C}$	26	A
$E_{AR}$	$T_C = 25^\circ\text{C}$	40	mJ
$E_{AS}$	$T_C = 25^\circ\text{C}$	1.0	J
$dv/dt$	$I_S \leq I_{DM}$ , $di/dt \leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$ , $R_G = 4 \Omega$	10	V/ns
$P_D$	$T_C = 25^\circ\text{C}$	400	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	1.6 mm (0.062 in.) from case for 10 s	300	$^\circ\text{C}$
$T_{SOLD}$	Plastic body for 10 s	260	$^\circ\text{C}$
$M_d$	Mounting torque (TO-247)	1.13/10	Nm/lb.in.
$F_C$	Mounting force (PLUS220)	11..65/2.5..15	N/lb
Weight	TO-247	6	g
	PLUS220 & PLUS220SMD	5	g

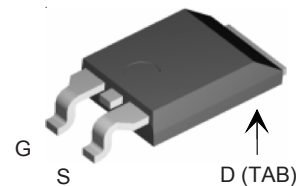
TO-247 (IXFH)



PLUS220 (IXFV)



PLUS220SMD (IXFV\_S)



G = Gate      D = Drain  
S = Source      TAB = Drain

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 4 \text{ mA}$	3.0		5.5 V
$I_{GSS}$	$V_{GS} = \pm 30 \text{ V}_{DC}$ , $V_{DS} = 0$			$\pm 100 \text{ nA}$
$I_{DSS}$	$V_{DS} = V_{DSS}$ $V_{GS} = 0 \text{ V}$ $T_J = 125^\circ\text{C}$			25 $\mu\text{A}$
				250 $\mu\text{A}$
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$ , $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2 \%$			230 $\text{m}\Omega$

### Features

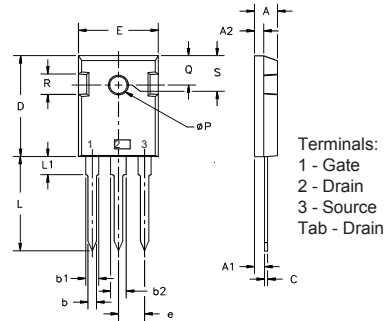
- † International standard packages
- † Fast intrinsic diode
- † Unclamped Inductive Switching (UIS) rated
- † Low package inductance
  - easy to drive and to protect

### Advantages

- † Easy to mount
- † Space savings
- † High power density

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = 20\text{ V}; I_D = 0.5 I_{D25}$ , pulse test	16	26	S
$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		3600	pF
$C_{oss}$			370	pF
$C_{rss}$			40	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 I_{D25}$ $R_G = 4\ \Omega$ (External)		20	ns
$t_r$			25	ns
$t_{d(off)}$			58	ns
$t_f$			20	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$		60	nC
$Q_{gs}$			20	nC
$Q_{gd}$			25	nC
$R_{thJC}$	(TO-247, PLUS220)			0.31 °C/W
$R_{thCS}$			0.21	°C/W

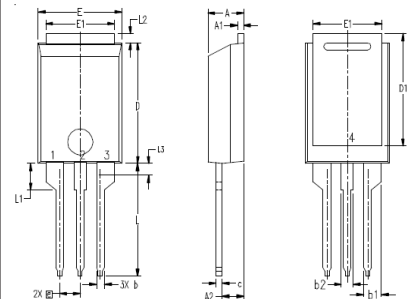
### TO-247 AD (IXFH) Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A <sub>1</sub>	2.2	2.54	.087	.102
A <sub>2</sub>	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b <sub>1</sub>	1.65	2.13	.065	.084
b <sub>2</sub>	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L <sub>1</sub>		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
$I_S$	$V_{GS} = 0\text{ V}$			26 A
$I_{SM}$	Repetitive			104 A
$V_{SD}$	$I_F = I_S, V_{GS} = 0\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$			1.5 V
$t_{rr}$	$I_F = 25\text{ A}, -di/dt = 100\text{ A}/\mu\text{s}$ $V_R = 100\text{ V}, V_{GS} = 0\text{ V}$			200 ns
$Q_{RM}$			0.6	$\mu\text{C}$
$I_{RM}$			6	A

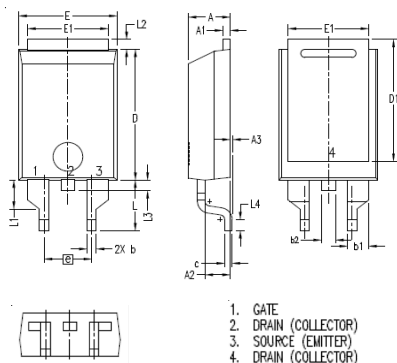
### PLUS220 (IXFV) Outline



1. GATE
2. DRAIN (COLLECTOR)
3. SOURCE (EMITTER)
4. DRAIN (COLLECTOR)

SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A <sub>1</sub>	.028	.035	0.70	0.90
A <sub>2</sub>	.098	.118	2.50	3.00
A <sub>3</sub>	.000	.010	0.00	0.25
b	.035	.047	0.90	1.20
b <sub>1</sub>	.080	.095	2.03	2.41
b <sub>2</sub>	.054	.064	1.37	1.63
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D <sub>1</sub>	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E <sub>1</sub>	.331	.346	8.40	8.80
e	.100	BSC	2.54	BSC
L	.512	.551	13.00	14.00
L <sub>1</sub>	.118	.138	3.00	3.50
L <sub>2</sub>	.035	.051	0.90	1.30
L <sub>3</sub>	.047	.059	1.20	1.50

### PLUS220SMD (IXFV\_S) Outline

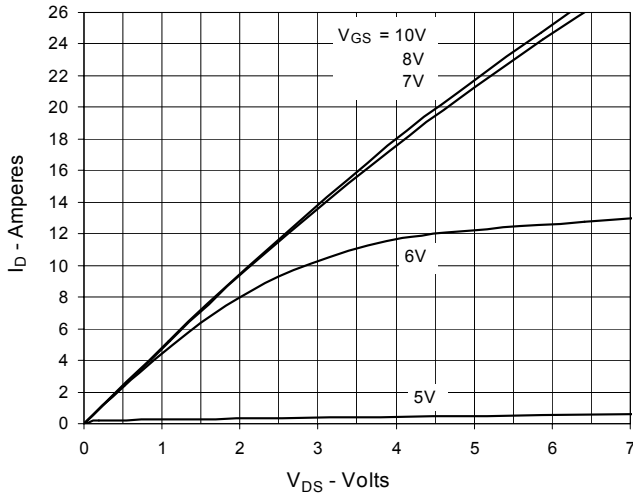
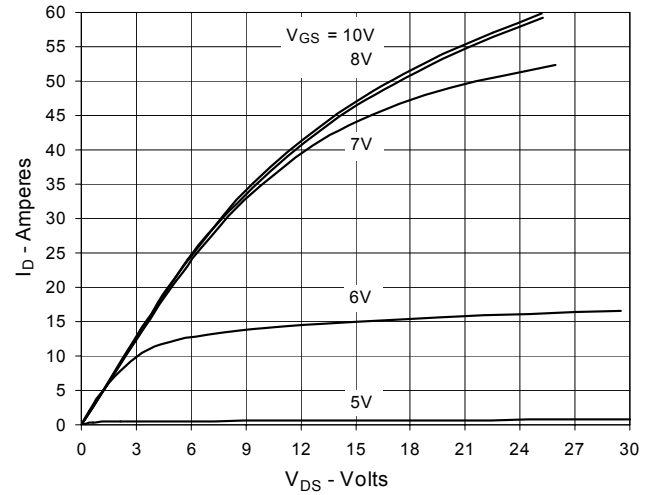
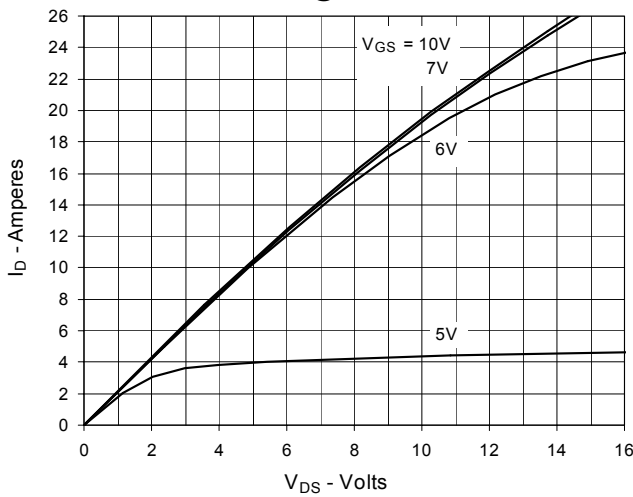
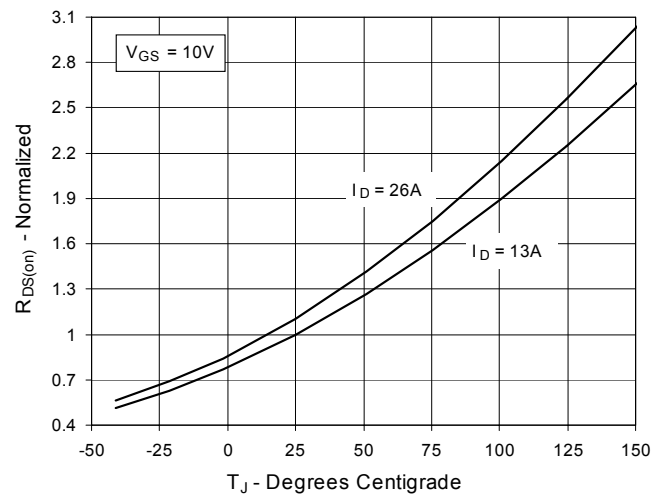
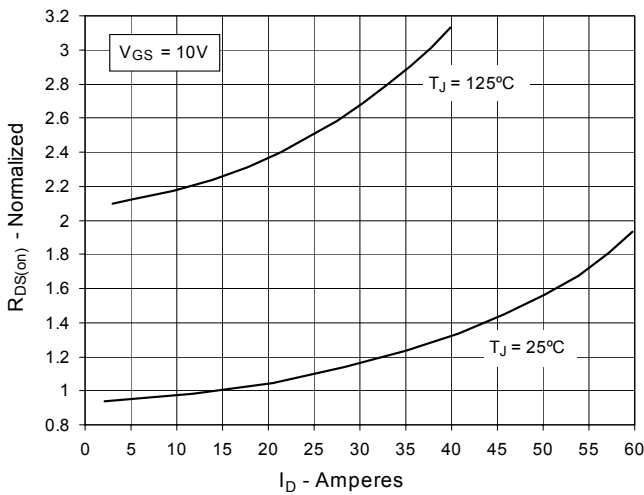
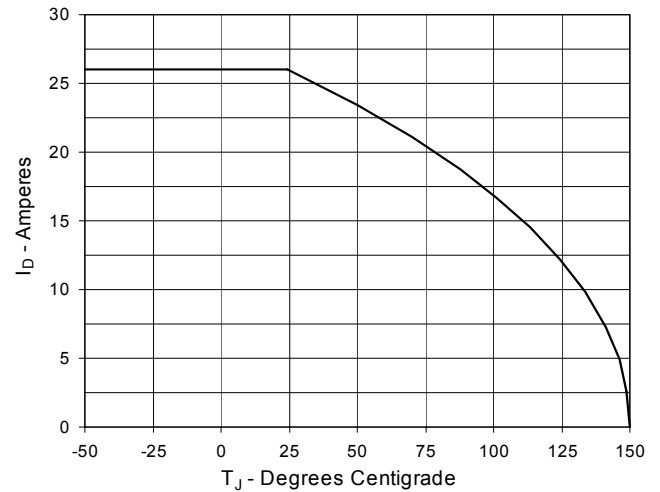


1. GATE
2. DRAIN (COLLECTOR)
3. SOURCE (EMITTER)
4. DRAIN (COLLECTOR)

SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A <sub>1</sub>	.028	.035	0.70	0.90
A <sub>2</sub>	.098	.118	2.50	3.00
A <sub>3</sub>	.000	.010	0.00	0.25
b	.035	.047	0.90	1.20
b <sub>1</sub>	.080	.095	2.03	2.41
b <sub>2</sub>	.054	.064	1.37	1.63
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D <sub>1</sub>	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E <sub>1</sub>	.331	.346	8.40	8.80
e	.200	BSC	5.08	BSC
L	.209	.228	5.30	5.80
L <sub>1</sub>	.118	.138	3.00	3.50
L <sub>2</sub>	.035	.051	0.90	1.30
L <sub>3</sub>	.047	.059	1.20	1.50
L <sub>4</sub>	.039	.059	1.00	1.50

IXYS reserves the right to change limits, test conditions, and dimensions.

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 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2

**Fig. 1. Output Characteristics  
@ 25°C**

**Fig. 2. Extended Output Characteristics  
@ 25°C**

**Fig. 3. Output Characteristics  
@ 125°C**

**Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 13A$  Value  
vs. Junction Temperature**

**Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 13A$  Value  
vs. Drain Current**

**Fig. 6. Maximum Drain Current vs.  
Case Temperature**


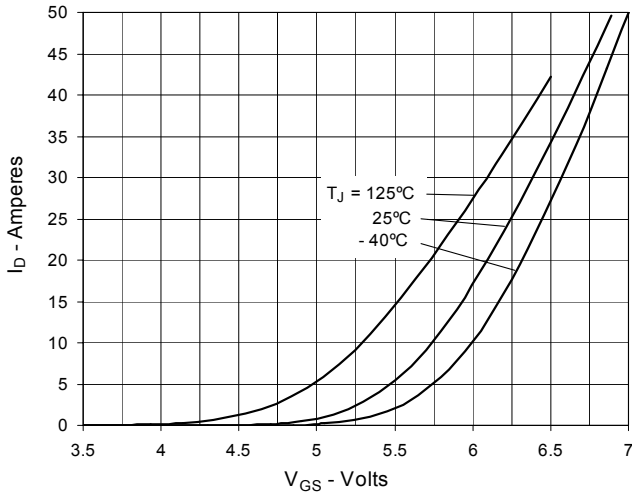
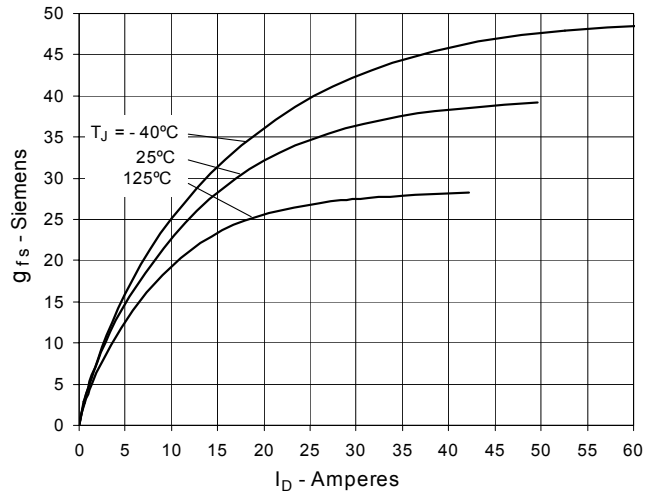
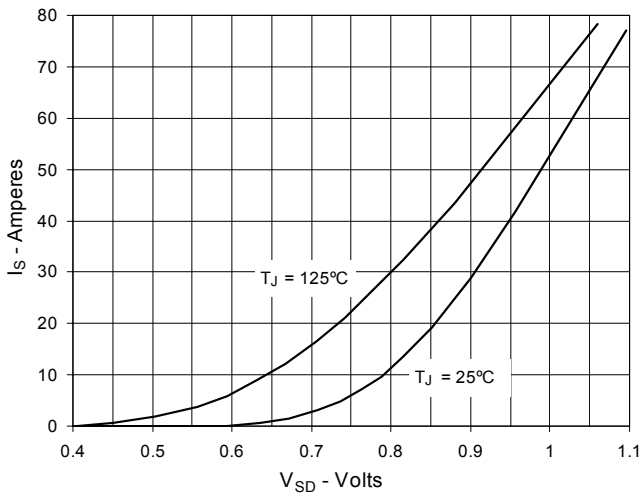
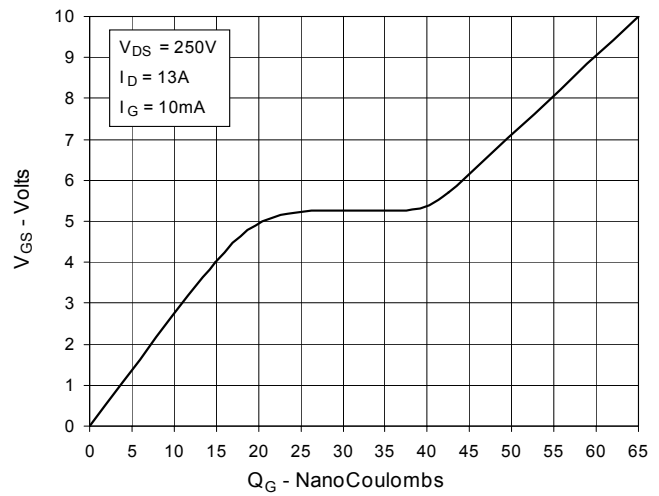
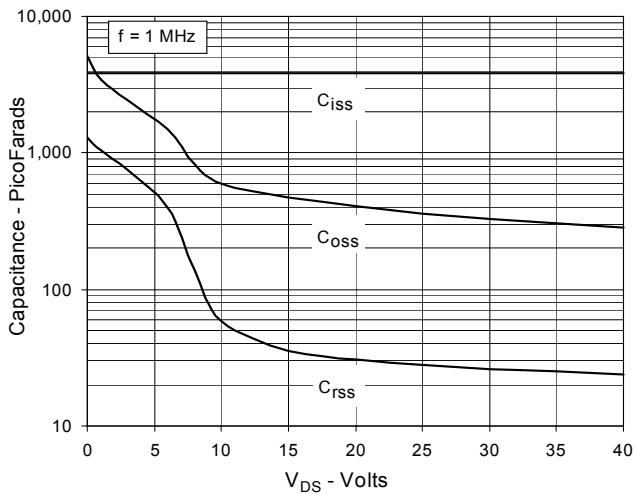
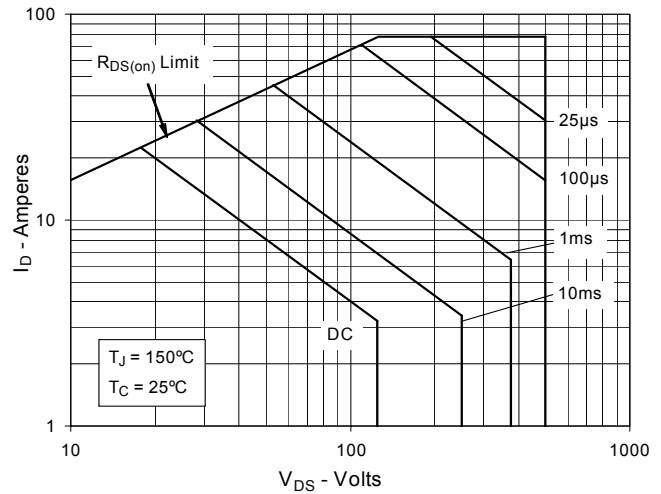
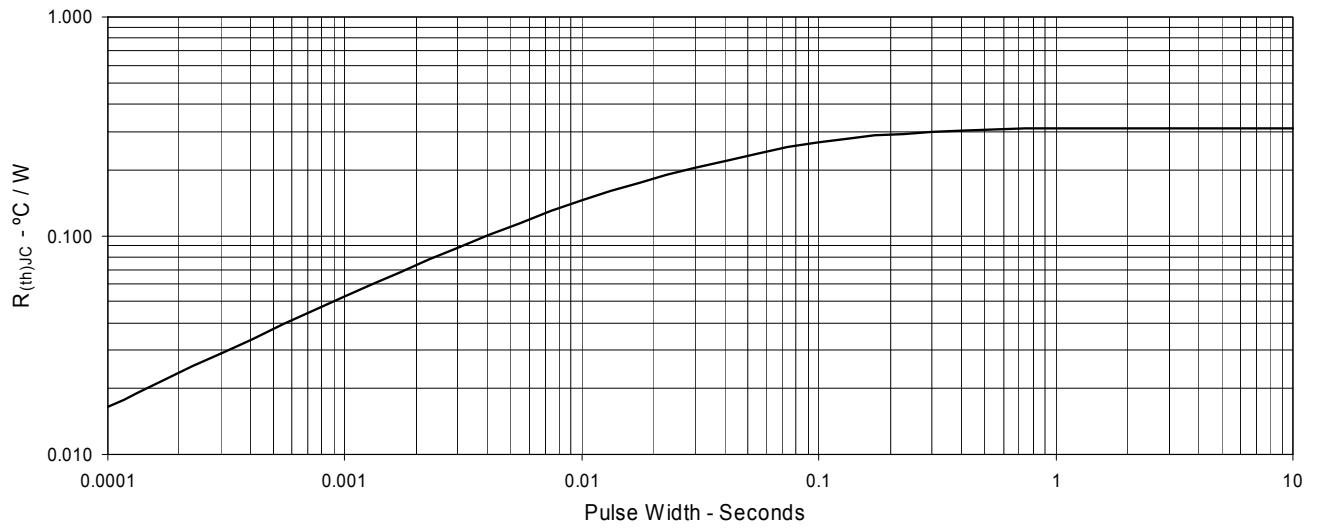
**Fig. 7. Input Admittance**

**Fig. 8. Transconductance**

**Fig. 9. Forward Voltage Drop of Intrinsic Diode**

**Fig. 10. Gate Charge**

**Fig. 11. Capacitance**

**Fig. 12. Forward-Bias Safe Operating Area**


Fig. 13. Maximum Transient Thermal Resistance





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